

In the Claims:

Please enter the following amended claims 1, 9, 11 and 19:

1. (Once Amended) A structure comprising:

a laminate substrate having a top surface for receiving a semiconductor die;

an antenna situated on a bottom surface of said laminate substrate, said antenna

A1 being suitable for connection to said semiconductor die;

a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;

at least one laminate substrate reference via situated at a side of said antenna.

A2 9. (Once Amended) The structure of claim 1 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

11. (Once Amended) A structure comprising:

A3 a laminate substrate having a top surface for receiving a semiconductor die;

an antenna situated on a bottom surface of said laminate substrate, said antenna being suitable for connection to said semiconductor die;

a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;

A3
Cont.

a plurality of laminate substrate reference vias, each of said plurality of laminate substrate reference vias situated at a side of said antenna.

A4

19. (Once Amended) The structure of claim 11 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.
